

Title (en)

METHOD FOR ENCAPSULATING INTEGRATED CIRCUITS.

Title (de)

VERKAPSELUNGSVERFAHREN FÜR INTEGRIERTE SCHALTUNGEN.

Title (fr)

PROCEDE D'ENCAPSULATION DE CIRCUITS INTEGRES.

Publication

EP 0264416 A1 19880427 (FR)

Application

EP 87902560 A 19870429

Priority

FR 8606333 A 19860430

Abstract (en)

[origin: WO8706763A1] For encapsulating integrated circuits mounted on a continuous dielectric strip (10) (surface-mounted circuits), it is proposed to cast by transfer a thermo-setting resin around the circuits carried by the strip, the injection of resin occurring outside the mating plane of the mould, contrary to what is usually done in this field. The protection of circuits is improved while preserving the testability on the strip.

Abstract (fr)

Pour l'encapsulation des circuits intégrés montés sur bande continue diélectrique (10) (circuits montables en surface), on propose de mouler par transfert une résine thermodurcissable autour des circuits portés par la bande, l'injection de résine se faisant en dehors du plan de joint du moule contrairement à ce qui est habituel dans ce domaine. On améliore la protection des circuits en conservant la testabilité sur bande.

IPC 1-7

H01L 21/56

IPC 8 full level

B29C 45/14 (2006.01); **B29C 70/72** (2006.01); **H01L 21/56** (2006.01)

CPC (source: EP KR US)

B29C 45/14655 (2013.01 - EP US); **B29C 70/72** (2013.01 - EP US); **H01L 21/56** (2013.01 - KR); **H01L 21/565** (2013.01 - EP US); **H01L 2224/45144** (2013.01 - EP US); **H01L 2224/48091** (2013.01 - EP US); **H01L 2224/48247** (2013.01 - EP US); **H01L 2924/15747** (2013.01 - EP US); **H01L 2924/3025** (2013.01 - EP US); **Y10T 29/49121** (2015.01 - EP US); **Y10T 29/49158** (2015.01 - EP US); **Y10T 29/49172** (2015.01 - EP US)

C-Set (source: EP US)

1. **H01L 2224/48091 + H01L 2924/00014**
2. **H01L 2924/15747 + H01L 2924/00**
3. **H01L 2924/3025 + H01L 2924/00**
4. **H01L 2224/45144 + H01L 2924/00**

Citation (search report)

See references of WO 8706763A1

Designated contracting state (EPC)

AT BE CH DE FR GB IT LI LU NL SE

DOCDB simple family (publication)

EP 0244322 A1 19871104; **EP 0244322 B1 19910612**; AT E64493 T1 19910615; DE 3770691 D1 19910718; EP 0264416 A1 19880427; FR 2598258 A1 19871106; FR 2598258 B1 19881007; JP 2759083 B2 19980528; JP S63503265 A 19881124; KR 880701460 A 19880727; US 4857483 A 19890815; WO 8706763 A1 19871105

DOCDB simple family (application)

EP 87400986 A 19870429; AT 87400986 T 19870429; DE 3770691 T 19870429; EP 87902560 A 19870429; FR 8606333 A 19860430; FR 8700143 W 19870429; JP 50280087 A 19870429; KR 870701258 A 19871230; US 14865587 A 19871229